



## Product Change Notification / JAON-18TQGC397

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**Date:**

10-May-2023

**Product Category:**

Broadband Gateway

**PCN Type:**

Manufacturing Change

**Notification Subject:**

CCB 5014.001 and 6259 Final Notice: Qualification of a new die size (1.932x1.860mm) for Die #1 of selected Microsemi LE9641PQC, LE9651PQC, LE9641PQCT, and LE9651PQCT catalog part numbers (CPN) available in 48L VQFN (7x7x1.0mm) package assembled at MMT assembly site.

**Affected CPNs:**

[JAON-18TQGC397\\_Affected\\_CPN\\_05102023.pdf](#)

[JAON-18TQGC397\\_Affected\\_CPN\\_05102023.csv](#)

**Notification Text:**

**PCN Status:**Final Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of a new die size (1.932x1.860mm) for Die #1 of selected Microsemi LE9641PQC, LE9651PQC, LE9641PQCT, and LE9651PQCT catalog part numbers (CPN) available in 48L VQFN (7x7x1.0mm) package assembled at MMT assembly site.

**Pre and Post Change Summary:**

	Pre Change	Post Change
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Fabrication Location	Die # 1	Global Foundries, Singapore - Fab 7 (GF07)		Global Foundries, Singapore - Fab 7 (GF07)	
	Die # 2	Global Foundries, Singapore - Fab 2 (GF02)	Microchip Technology Colorado – Fab 5 (MCSO)	Global Foundries, Singapore - Fab 2 (GF02)	Microchip Technology Colorado – Fab 5 (MCSO)
Die Size	Die # 1	2.204 x 2.258 mm		1.932x1.860mm	
		Please see attached pre and post change comparison for Die # 1 Location			
	Die # 2	1.57 x 1.72 mm		1.57 x 1.72 mm	
Assembly Site		Microchip Technology Thailand (Branch) (MMT)		Microchip Technology Thailand (Branch) (MMT)	
Wire Material		CuPdAu		CuPdAu	
Die Attach Material		3280		3280	
Molding Compound Material		G700LTD		G700LTD	
Lead Frame Material		A194		A194	

**Impacts to Data Sheet:**None

**Change Impact:**None

**Reason for Change:**To improve productivity by qualifying a new die size.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**May 15, 2023 (date code: 2320)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	May 2022					>	May 2023				
Workweek	1 9	2 0	2 1	2 2	2 3		1 8	1 9	2 0	2 1	22
Initial PCN Issue Date			X								
Qual Report								X			

Availability												
Final PCN Issue Date								X				
Estimated Implementation Date									X			

**Method to Identify Change:**Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**May 24, 2022: Issued initial notification.  
May 10, 2023: Issued final notification. Attached Qual report and added the estimated first ship date May 15, 2023.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

## Attachments:

[PCN\\_JAON-18TQGC397\\_Qualification Report.pdf](#)  
[PCN\\_JAON-18TQGC397\\_Pre and Post Change\\_Summary.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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